Materials Declaration

Package	LQFP - PQ2
Body Size	14 X 14 x 1.4
LeadCount	80
Option	Pb Free

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	88.0	2.92 E-01	255283
Multi-aromatic Resin	11.5	3.82 E-02	33361
Carbon Black	0.5	1.66 E-03	1451

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.25	9.74 E-02	85055
Cr	0.30	2.94 E-04	257
Sn	0.25	2.45 E-04	214
Zn	0.20	1.96 E-04	171

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	6.00 E-04	524

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	100.0	6.37 E-03	5562

External Heat Sink Plating

Item	% of Plating	Weight (g)	PPM
Ni	100.0	1.63 E-03	1422

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	2.80 E-03	2444

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	3.29 E-02	28775

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	70.0	3.41 E-03	2976
Resin	20.0	9.74 E-04	851
Anhydride	10.0	4.87 E-04	425

Heat Sink

	% of Heat Sink	Weight (g)	PPM
Cu	100	6.65 E-01	581229

Molding Compound

Item	PPM	Method
Pb	None Detected	US EPA 3050B. ICP-AES
Cd	None Detected	EN 1122:2001. ICP-AES
Hg	None Detected	US EPA 3052. ICP - AES
Cr+6	None Detected	US EPA 3060A & 7196A.
PBB	None Detected	US EPA 3540C. Analysis performed by HPLC/DAD, LC/MS or GC/MS
PBDE	None Detected	US EPA 3540C. Analysis performed by HPLC/DAD, LC/MS or GC/MS

Die Attach Paste

Item	PPM	Method
Pb	None Detected	US EPA 3052. ICP -OES
Cd	None Detected	US EPA 3052. ICP -OES
Hg	None Detected	US EPA 3052. ICP -OES
Cr+6	None Detected	US EPA 3060A & 7196A . UV-VIS
PBB	None Detected	SGS-in house method. Analysis performed by GC/MS
PBDE	None Detected	SGS-in house method. Analysis performed by GC/MS

Package Totals

Weight (g)	PPM
1.14 E+00	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information

ANALOG DEVICES

ADI Proprietary

Materials Declaration

Package	LQFP- PQ2
Body Size	14 X 14 x 1.4
LeadCount	80
Option	Sn/Pb

Molding Compound

Item	% of Compound	Weight (g)	PPM
SiO2 Filler	86.0	2.89 E-01	251264
Biphenyl Resin	13.2	4.41 E-02	38420
Sb2O3	0.5	1.68 E-03	1461
Br	0.4	1.17 E-03	1022

Leadframe

Item	% of Leadframe	Weight (g)	PPM
Cu	99.25	9.74 E-02	84793
Cr	0.30	2.94 E-04	256
Sn	0.25	2.45 E-04	213
Zn	0.20	1.96 E-04	171

Internal Leadframe Plating

	% of Plating	Weight (g)	PPM
Ag	100.0	6.00 E-04	522

External Leadframe Plating

Item	% of Plating	Weight (g)	PPM
Sn	85.0	5.86 E-03	5101
Pb	15.0	1.03 E-03	900

External Heat Sink Plating

Item	% of Plating	Weight (g)	PPM
Ni	100.0	1.63 E-03	1418

Bond Wires

	% of Wire	Weight (g)	PPM
Au	99.99	2.80 E-03	2437

Chip

	% of Chip	Weight (g)	PPM
Si	100.0	3.29 E-02	28686

Die Attach

Item	% of Die Attach	Weight (g)	PPM
Ag Filler	70.0	3.13 E-03	2726
Diglycidylether of bisphenol-F	10.0	4.47 E-04	389
Resin	7.0	3.13 E-04	273
Amine	5.0	2.24 E-04	195
Gamma Butyrolactone	5.0	2.24 E-04	195
Mixed aryl allyl glycidyl compounds	3.0	1.34 E-04	117

Heat Sink

	% of Heat Sink	Weight (g)	PPM
Cu	100.0	6.65 E-01	579440

Package Totals

Weight (g)	PPM
1.15 E+00	1000000

Molding Compound

Item	PPM	Method
Pb	None Detected	US EPA 3050B. Analysis was performed by ICP-AES
Cd	None Detected	EN 1122 Method B. Analysis was performed by ICP-AES
Hg	None Detected	US EPA 3052. Analysis was performed by ICP-AES
Cr+6	None Detected	EPA 3060A & 7196A
PBB	None Detected	US EPA 3540 or 3550. Analysis by HPLC/DAD, LC/MS or GC/MS
PBDE	None Detected	US EPA 3540 or 3550. Analysis by HPLC/DAD, LC/MS or GC/MS

Die Attach Paste

Item	PPM	Method
Pb	3.0 ppm	US EPA 3052. ICP -OES
Cd	None Detected	US EPA 3052. ICP -OES
Hg	None Detected	US EPA 3052. ICP -OES
Cr+6	None Detected	US EPA 3060A & 7196A . UV-VIS
PBB	None Detected	SGS-in house method. Analysis performed by GC/MS
PBDE	None Detected	SGS-in house method. Analysis performed by GC/MS

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ANALOG DEVICES